

INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Application No.	10/822,424
		Filing Date	April 12, 2004
		First Named Inventor	Bulent M. Basol
		Art Unit	1742 1795
(Multiple sheets used when necessary)		Examiner	Zulmariam Mendez
SHEET 1 OF 2		Attorney Docket No.	NVLUS.029CP1(5296)

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Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T ¹
/Z.M./	4	DE 2008664	09-09-1971	Jostan		
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	7	GB 1350070	04-18-1974	Luttmer et al.		
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	9	JP 11-054479	02-26-1999	Nakajima		
	10	WO 97/01657	01-16-1997	Billman		
	11	WO 98/27585	06-25-1998	Andricacos et al.		
	12	WO 99/64647	12-16-1999	Adams et al.		
	13	WO 00/03426	01-20-2000	Wang et al.		
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/Z.M./	15	WO 02/064314	08-22-2002	Emesh et al.		

NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
/Z.M./	16	Contolini et al., "Electrochemical Planarization for Multilevel Metallization," J. Electrochem. Soc., 1994, Vol. 141, pp. 2503-2510.	
/Z.M./	17	Kelly et al, "Leveling and Microstructural Effects of Additives for Copper Electrodeposition," J. Electrochem. Soc., 1999, Vol. 146, No. 7, pp. 2540-2545.	
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Examiner Signature	/Zulmariam Mendez/	Date Considered	10/28/2007
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*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T¹ - Place a check mark in this area when an English language Translation is attached.

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Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
/Z.M./	20	Rubinstein, "Tampongalvanisieren in der Praxis, Teil 1," <u>Galvanotechnik</u> , 1988, Vol. 79, No. 10, pp. 3263-3270.	
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/Z.M./	24	Office Action for U.S. Patent Application No. 10/391,924, dated April 30, 2007	
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